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(54) Title: POLISHING PAD WITH POROUS INTERFACE AND SOLID CORE, AND RELATED APPARATUS AND METHODS

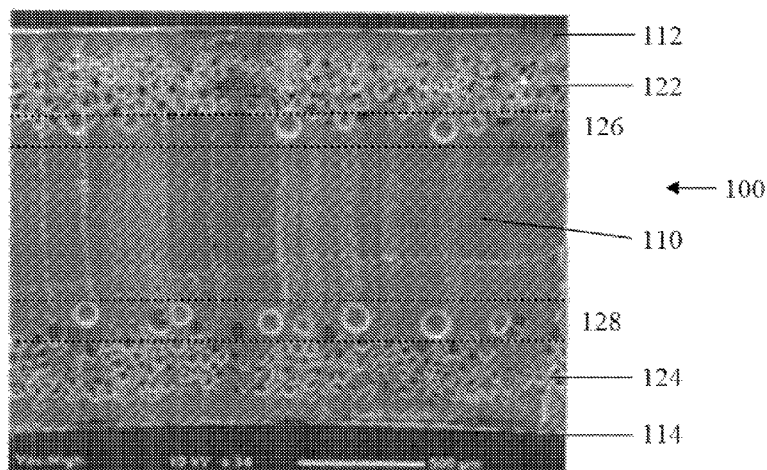


FIG. 1

(57) Abstract: Disclosed is a polishing pad for chemical-mechanical polishing. The polishing pad has a porous interface and a substantially non-porous bulk core. Also disclosed are related apparatus and methods for using and preparing the polishing pad.